IN THE CLAIMS

Amendments To The Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1 and 9 are amended.

Listing of Claims:

1. (Currently Amended) A semiconductor device comprising:

a semiconductor chip;

a mold resin sealing the semiconductor chip; and

a plurality of conductor leads extending from an inside of the mold resin to an outside thereof, each having a portion arranged inside the mold resin defining an internal terminal portion and a portion arranged outside the mold resin defining an external terminal portion, and an electrode of the semiconductor chip and the internal terminal portion of the conductor lead being connected;

wherein ~~the internal terminal portion of~~ at least one of the conductor leads has ~~an~~ two inductance element ~~portion~~ portions, ~~with a width narrower than the external terminal portion,~~

an additional external terminal portion is branched off from between the two inductance element portions,

the inductance element portions [[has]] have a meandering planar shape, and

the conductor lead with the inductance element portions has an overlapping portion overlapping a lower surface of the semiconductor chip at which the semiconductor ship is mounted on and connected with the conductor lead.

2-3. (Canceled)

4. (Previously Presented) The semiconductor device according to claim 1, wherein in the overlapping portion of the electrode of the semiconductor chip and the conductor

lead, the connection is made via an electrical conductor in a via hole formed in the semiconductor chip.

5. (Previously Presented) The semiconductor device according to claim 1, wherein the overlapping portion of the conductor lead forms a die pad portion on which the semiconductor chip is mounted.

6. (Original) The semiconductor device according to claim 1, wherein the conductor lead having the inductance element portion is connected to a source of a field–effect transistor or an emitter of a bipolar transistor formed in the semiconductor chip.

7. (Original) The semiconductor device according to claim 1, wherein the conductor lead having the inductance element portion is connected to a gate or a drain of a field–effect transistor or a base or a collector of a bipolar transistor formed in the semiconductor chip.

8. (Original) The semiconductor device according to claim 1, wherein at least one of the conductor leads functions as a choke inductor or matching element.

9. (Currently Amended) A semiconductor device comprising:

a semiconductor chip;

a mold resin sealing the semiconductor chip; and

a plurality of conductor leads extending from an inside of the mold resin to an outside thereof, each having a portion arranged inside the mold resin defining an internal terminal portion and a portion arranged outside the mold resin defining an external terminal portion, and an electrode of the semiconductor chip and the internal terminal portion of the conductor lead being connected;

wherein ~~each of the internal terminal portions of~~ at least two of the conductor leads have ~~having the same shape has an~~ two inductance element ~~portion~~ portions ~~with a width narrower than the external terminal portion~~, ~~and~~

an additional external terminal portion is branched off from between the two inductance element portions,

the two internal terminal portions are arranged symmetrically with respect to the semiconductor chip, with the semiconductor chip being interposed therebetween, and

a width of the inductance element portion connected to the external terminal portion is larger than a width of the inductance element portion connected to the internal terminal portion.